

ID	R _{DS} (ON)(Typ)	VDSS
45A	0.105Ω	500V

Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Features:

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability
- Fast Recovery Time

Ordering Information

GDS	G
RoHS	REACH HF

Part Number	Package	Marking	Packing	Qty.
RSF45N50W	T0-247-3	RSF45N50W	Tube	30 PCS

Absolute Maximun Ratings Tc= 25°C unless otherwise specified

Symbol	Parameter	RSF45N50W	Units
VDSS	Drain-to-Source Voltage	500	V
ID	Continuous Drain Current TC=25℃	45	
IDM	Pulsed Drain Current (Note*1)	180	A
PD	Power Dissipation	250	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Engergy L = 10mH,,VDD = 50V, RG = 25 Ω	2580	mJ
TL TPKG	Maximum Temperature for Soldering Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds	300 260	Ĉ
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the" Absolute Maximum Ratings" Table may cause permanent damage to the device.



Thermal Resistance

Symbol	Parameter	RSF45N50W	Units	Test Conditions
				Drain lead soldered to water cooled
RθJC	Junction-to-Case	0.5		heatsink, PD adjusted for a peak
			°C/W	junction temperature of + 1 5 0 $^\circ \! \mathbb{C}$
	Junction-to-	40		1 subis fact shamber free sir
RθJA	Ambient	40		1 cubic foot chamber,free air.

OFF Characteristics TJ= 25° C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	500			V	VGS=0V,ID=250µA
IDSS	Drain- to- Source Leakage Current			1	μA	VDS=500V,VGS=0 V
	Gate- to- Source Forward Leakage			100		VGS=30V,VDS=0V
IGSS	Gate- to- Source Reverse Leakage			-100	nA	VGS=-30V ,VDS=0 V

ON Characteristics TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On- Resistance(Note*2)		0.105	0.12	Ω	VGS=10V,ID=22.5 A
VGS(TH)	Gate Threshold Voltage	3		4	V	VGS=VDS,ID=250µ A

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time		66			
trise	Rise Time		85		~6	VDS=250V ID=45A
td(OFF)	Turn- OFF Delay Time		370		nS	VGS=10V RG=25Ω
tfall	Fall Time		160			



Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Ciss	Input Capacitance		7890			VGS=0V
Coss	Output Capacitance		678		pF	VDS=25V
Crss	Reverse Transfer Capacitance		10			f=1.0MHz
Qg	Total Gate Charge		126			VDS=400V
Qgs	Gate- to- Source Charge		36		nC	ID=45A
Qgd	Gate-to-Drain(" Miller") Charge		32			VGS=10V

Source- Drain Diode Characteristics

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
IS	Continuous Source Current			45	А	Integral pn- diode
ISM	Maximum Pulsed Current			180	А	in MOSFET
VSD	Diode Forward Voltage			1.4	V	IS=22.5A,VGS=0V
trr	Reverse Recovery Time		130		nS	VGS=0V
Qrr	Reverse Recovery Charge		0.57		μC	IS=45A,di/dt=100A /μs

Notes:

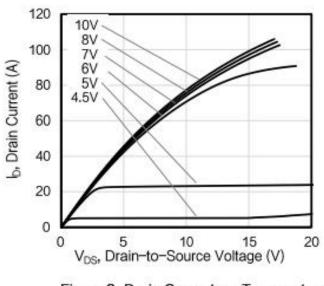
* 1. Repetitive rating, pulse width limited by maximum junction temperature.

* 2. Pulse Test: Pulse width \leq 300µs, Duty Cycle \leq 1%

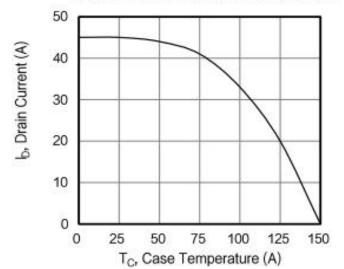


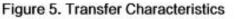
Typical Feature Curve

Figure 1. Output Characteristics (T_J = 25°C)









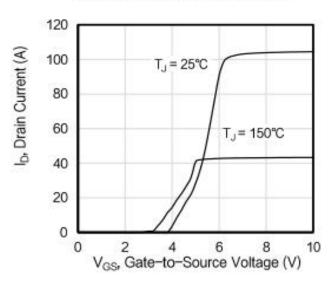
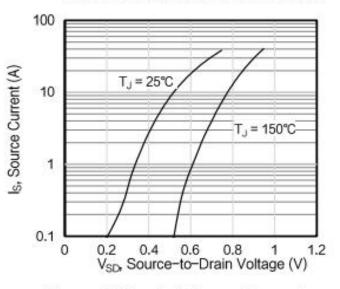


Figure 2. Body Diode Forward Voltage





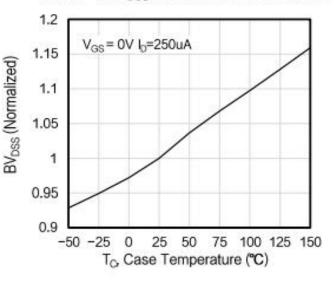
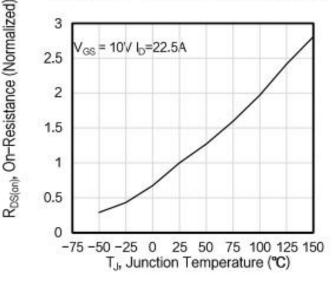
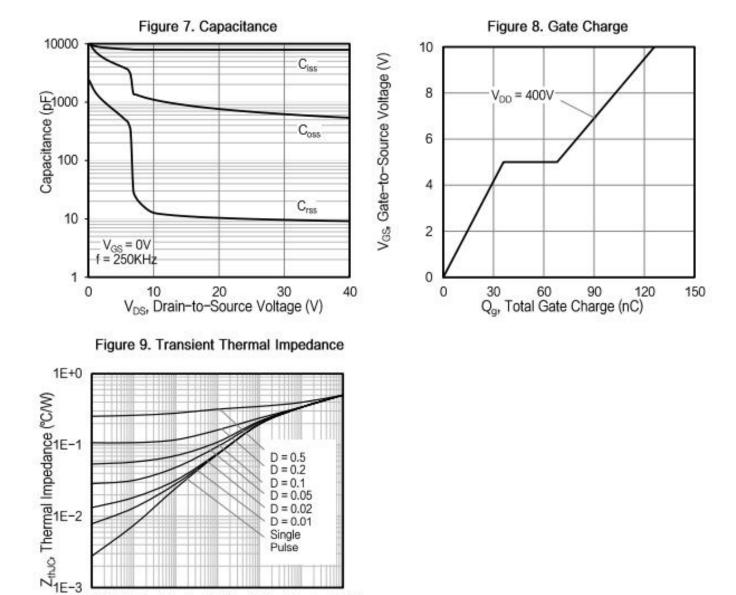


Figure 6. On-Resistance vs. Temperature







D = 0.5 D = 0.2 D = 0.1 D = 0.05 D = 0.02 D = 0.01 Single Pulse

1E-1

1E+0

1E-3

T_p, Pulse Width (s)

1E-2

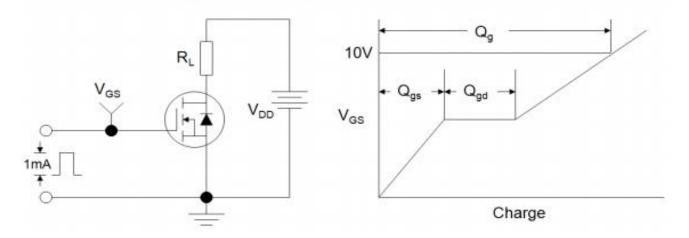
1E-4

1E-6 1E-5



Test Circuits and Waveforms







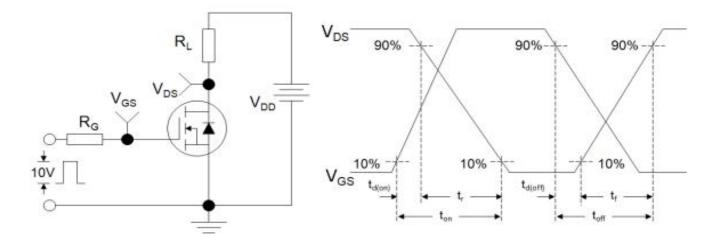
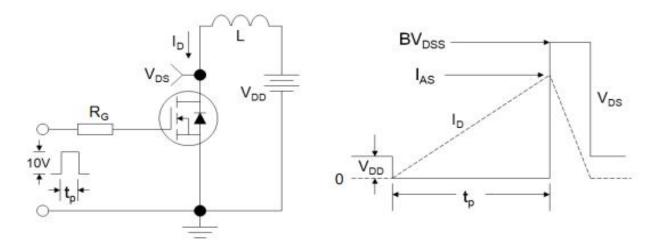
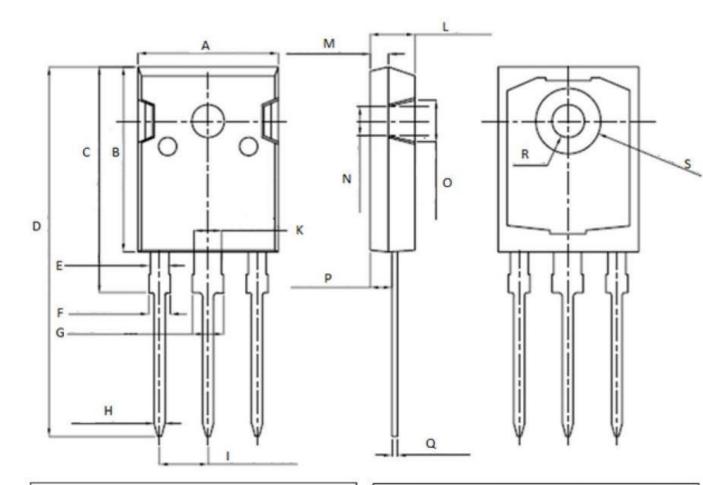


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





Package outline drawing(TO-247 Unit: mm)



	Unit: mm	
Symbol	Min.	Max.
Α	15.95	16.25
В	20.85	21.25
C	20.95	21.35
D	40.5	40.9
E	1.9	2.1
F	2.1	2.25
G	3.1	3.25
Н	1.1	1.3
1	5.40	5.50

	Unit: mm	
Symbol	Min.	Max.
K	2.90	3.10
L	4.90	5.30
Μ	1.90	2.10
N	4.50	4.70
0	5.40	5.60
Ρ	2.29	2.49
Q	0.51	0.71
R	φ3.5	φ3.7
S	φ7.1	φ7.3



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